

Integrated Circuit, Hybrid, and Multichip Module Package Design Guidelines: A Focus on Reliability (Hardback)



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Reviews

This written publication is wonderful. It really is loaded with knowledge and wisdom You will not really feel monotony at at any time of your time (that's what catalogues are for relating to if you ask me).

(Desmond Becker)

INTEGRATED CIRCUIT, HYBRID, AND MULTICHIP MODULE PACKAGE DESIGN GUIDELINES: A FOCUS ON RELIABILITY (HARDBACK)



John Wiley & Sons Inc, United States, 1994. Hardback. Condition: New. Language: English. Brand new Book. Circuit designers, packaging engineers, printed board fabricators, and procurement personnel will find this book a s microelectronic package design--for--reliability guidelines and approaches essential for achieving their life--cycle, cost--effectiveness, and on--time delivery goals. Its uniquely organized, time--phased approach to design, development, qualification, manufacture, and in--service management shows you step--by--step how to: aeo Define realistic system requirements in terms of mission profile, operating life, performance expectations, size, weight, and cost aeo Define the system usage environment so that all operating, shipping, and storage conditions, including electrical, thermal, radiation, and mechanical loads, are assessed using realistic data aeo Identify potential failure modes, sites, mechanisms, and architecture--stress interactions----PLUS appropriate measures you can take to reduce, eliminate, or accommodate expected failures aeo Characterize materials and processes by the key controllable factors, such as types and levels of defects, variations in material properties and dimensions, and the manufacturing and assembly processes involved aeo Use experiment, step--stress, and accelerated methods to ensure optimum design before production begins Detailed design guidelines for substrate.wire and wire, tape automated, and flip--chip bonding.element attachment and case, lead, lead and lid seals----incorporating dimensional and geometric configurations of package elements, manufacturing and assembly conditions, materials selection, and loading conditions----round out this guide a s comprehensive tailed guidelines for substrate.wire and wire, tape automated, and flip--chip bonding.element attachment and case, lead, lead and lid seals----incorporating dimensional and geometric configurations of package elements, manufacturing and assembly conditions, materials selection, and loading conditions----round out this guide a s comprehensive coverage. of related interest. PHYSICAL ARCHITECTURE OF VLSI SYSTEMS ----Allan D. Kraus, Robert Hannemann and Michael Pecht For the professional engineer involved in the design and manufacture of products containing electronic components, here is a comprehensive handbook to the theory and methods surrounding the assembly of...



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